

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

M. Koike

Serial No.: Division of 10/090,787

Group Art Unit: Not Assigned

Filed: Concurrently

Examiner: Not Assigned

For: SEMICONDUCTOR DEVICE, RESIN SEALING METHOD AND RESIN  
SEALING DEVICE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## PRELIMINARY AMENDMENT

Sir:

Prior to the calculation of the filing fee of the above identified divisional application, please amend the application as follows:

In the specification:

After the title please insert --This application is a division of U.S. Patent application S.N. 10/090,787, filed March 6, 2002--.

In the claims:

Please delete claims 1-6 and 17-20.

Please amend the claims as follows. A clean copy of the amended claims is attached hereto.

9. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], wherein a plurality of said through openings and said resin flow passages are provided for performing filling of the resin at a plurality of portions.

14. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], wherein filling of said resin is performed through one or more through holes provided in said wired substrate for electrical connection.

15. (Amended) A resin seal process of a semiconductor device as set forth in claim 7 [or 8], which comprises step of setting a plurality of molding objects within the mold and clamping said mold for filling said resin for a plurality of semiconductor chips simultaneously.

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